





# NEXT-GENERATION MEMORY(MRAM) SUPPLIER





<sup>02</sup> Technology





Technology

### Test Technology & Quality Control

### In-House Wafer Test

### Quality Management

Quality control & monitor Yield improvement Feed Back to Foundry Technical analysis for test coverage Mass production test

# On Time Delivery

In-House Wafer Test Line



### SPC Control System

Control Yield & Special Bin [SBL Control] Statistical yield & subbin limit management







<sup>02</sup> Product-Line up

STT-MRAM

Status	Memory Type	Product	Applications
Mass Production Product	<b>STT-MRAM</b> [28nm]	1Mb~32Mb Single/Dual/Quad SPI 1Mb~64Mb PPI	Smart Meter, IoT, Industrial, Smart factory, Gaming Machine, etc.
Under Development	<b>STT-MRAM</b> [14nm]	128Mb~512Mb[1Gb] Octal SPI 128Mb~512Mb[1Gb] Single/Dual/Quad SPI	Automotive, Hearing Aids, Wearable, TWS, 5G, AloT, Medical, Enterprise Storage, etc.



# <sup>02</sup> Manufacturing Site

Manufacturing Site by Product

Product	Foundry	Wafer Test	Assembly	PKG Test
STT-MRAM 28nm[MP],14nm[UD]	SAMSUNG Samsung Foundry In Korea	Netsol	SFA Semicon Korea for BGA SFA Semicon SFA Semicon China for TSOP, WSON	SFA Semicon In Korea



SILES

# Next Generation Memory STT-MRAM

STT-MRAM with the high speed of DRAM and non-volatility of Flash Memory

# STT-MRAM Structure, MTJ(Magnetic Tunnel Junction)



# Advanced MRAM Technology, STT-MRAM



Non-volatile : Flash/ROM Like
Fast Write Time : DRAM Like
Endurance : Virtually unlimited

- Scalability : High Density
- Low power consumption





#### Next Generation Memory - MIRS S Working principle of STT-MRAM **STT-MRAM** [Logic "0"] [Logic "1"] [STT-MRAM] [PMTJ] BL=Vdd BL=0 Spin polarization Free Layer Barrier Layer Fixed Layer C SL=0 SL=Vdd WL (Gate) Parallel Polarization Anti-parallel Polarization The basic cell of Spin-Transfer Torque MRAM (STT-MRAM) MTJ=Low Resistance MTJ=High Resistance consists of one MTJ and one accessing transistor Si Substrate

 Store data "0" and "1" separately depending on the relative orientation of spin magnetization between the ferromagnetic free layer and the pinned layer

Pinned Layer	Free Layer	Resistance	Data
1	(parallel)	Low	0
1	↓ (antiparallel)	High	1



02

STT-MRAM Unified Memory's Convergence Trend

### MRAM is the best unified memory







# Next Generation Memory STT-MRAM

# **NETSOL 1<sup>st</sup> MRAM Products**



# **Process Technology**

• 28nm, Samsung Foundry



# • Serial Interface (SPI) STT-MRAM

Density	SPI Mode	Vcc	PKG	Operating Temp.	Speed (Operating Frequency)
1Mb / 2Mb / 4Mb / 8Mb / 16Mb / 32Mb	Single, Dual, Quad	3.3V 1.8V	8WSON ( 6x5mm) 8SOIC ( 150mil)	-40°C ~ 85°C	108MHz *133Mhz for 32Mb

\* Compatible with SPI-NOR, SPI-FRAM, SPI-pSRAM (IoT RAM)

# • Parallel Interface (PPI) STT-MRAM

Density	I/O Org.	Vcc	PKG	Operating Temp.	Speed (Access Time)
1Mb / 2Mb / 4Mb / 8Mb /16Mb / 32Mb/64Mb	x8/ x16	3.3V 1.8V	44TSOP2 54TSOP2 48FBGA (6x8mm)	-40°C ~ 85°C	70ns

\* Compatible with PPI FeRAM /low- power SRAM



# <sup>02</sup> Next Generation Memory STT-MRAM

**Comparison with FeRam** 



# Low price

- $\rightarrow$  MRAM price < FeRAM price
- $\rightarrow$  Advanced process : MRAM(28nm) vs FeRAM(90nm)
- High density
- → MRAM 32Mb > FeRAM 16Mb

# • High reliability/endurance

→ FeRAM :  $10^{13}$  read and write cycles MRAM :  $10^{14}$  write cycles

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	FeRAM	Winner	STT-MRAM
Endurance	10 <sup>13</sup> cycles (read and write)	<b>→</b>	10 <sup>14</sup> cycles (only write)
Density	1Kb~16Mb		1Mb~32Mb
Scalability	Not Good (90nm)		Good (28nm)
Price	High	$\rightarrow \rightarrow$	Low

\* The endurance of FeRAM is affected not only by write operation but also by read operation, but the endurance of MRAM is affected only by write operation. There are usually more read operations than write operations on the system. Considering this, MRAM's endurance can be said to be more than 20 times higher than that of FeRAM.



# Next Generation Memory STT-MRAM

Comparison with NOR

# \_MRAM Advantage

- Much faster write speed than NOR
  - $\rightarrow$  OTA(Over The Air)
  - $\rightarrow$  No extra RAM required
- Much longer write endurance
- $\rightarrow$  much longer life time

• No page/block size and fast write time

 $\rightarrow$  Efficient storage area utilization ex) 32Mb NOR being replaced with 16Mb MRAM

Contrass.

• Low write energy → very small write energy

	NOR	Winner	STT-MRAM
	Page Program Time : 0.4~3ms		tCSDW Time : 20~350ns
Write Speed	Sector Erase Time: 45~400ms	$\rightarrow \rightarrow$	No Erase Function Required
	Ex)1-sector erase/program time ~52ms		Ex) 1-sector write time ~ $0.083$ ms *
	P/E 10 <sup>5</sup> cycles	~~	Write 10 <sup>14</sup> cycles
	Wear leveling required``	77	No wear leveling required
Random Accessibility	Limited by page/block size and slow P/E time	$\rightarrow \rightarrow$	No Limit and fast write time
Write Energy	~6.8mJ (1-sector erase/program)	$\rightarrow \rightarrow$	~6.8uJ (1-sector write) *

IoT terminal example



[NOR case]



[ MRAM case ]



\* 4-4-4, 100MHz



# <sup>02</sup> Next Generation Memory STT-MRAM

**Comparison with SRAM** 

# **MRAM Advantage**

- No need of Battery
  - $\rightarrow$  Removing Battery, Battery socket, Vcc monitor circuit
  - $\rightarrow$  No Battery maintenance, reducing Cost of Quality

- $\rightarrow$  Simple SMT process
- → Longer Retention Time ; Battery 7 years, MRAM 10 years

	SRAM	Winner	STT-MRAM
Read /Write Speed*	55ns~70ns	<b>++</b>	70n/ 320ns ( 240ns as of Jan 2024)
Battery Requirement	YES	$\rightarrow \rightarrow$	NO
Retention Time	7 years (Battery Life Time)	<b>→</b>	10 years

\*Note : PPI interface

# Battery Backup System Example





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# **MRAM Applications**

### Multi Functional Printer



Industrial PC

INNAMES FA/PLC



Output Port



→ Not required when using MRAM

[Traditional] •Voltage Monitor/ Controller •Vcc Regulator •SRAM \*\*\*\*\* •Battery Socket Battery







# MRAM Applications

### Network Systems





# <sup>13</sup> MRAM Applications

### Medical Instruments



•Configuration Memory MRAM

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[Traditional]

Image/Report Memory
nvRAM

Capacito

Data Acquisition

System

.

Configuration Memory NOR

\*\*\*\*\*\*



Image/Report Memory
 MRAM

Data Acquisition

9<sub>stem</sub>

# Game Machine



[Traditional]



[with MRAM]







# <sup>03</sup> MRAM Applications

# Data Center/ Enterprise-SSD





# <sup>33</sup> MRAM Applications

# Server/RAID Controller Card



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# **MRAM Applications**

### Data Logging

#### Process of repeatedly collecting and storing important system data

- events for tracking
- history of usage - environmental parameters - status of the machine
- other data for analyzing purposes

; Requires fast write speeds, high number of repeat writes, non-volatile memory

- No need for batteries and capacitors
- Reduce quality control burden
- Replaces NOR Flash and FRAM with fast writing speed and high endurance
- Instant Data Backup and System recover





News

# • STT-MRAM info (Article Link) Posted : Aug.30.2023 by Ron Mertens

NETSOL launches a stand-alone STT-MRAM product fabricated in Samsung Foundry's 28nm FDSOI process



NETSOL MRAM products are ideal for applications that need to store and retrieve data quickly and frequently due to STT-MRAM's virtually unlimited endurance and fast-write features. Ideal for code storage, data logging, backup and working memory in industrial devices/ equipment, it can replace NOR Flash, FeRAM, low-power SRAM and nvSRAM products, among others with unmatched performance and non-volatile features.

"NETSOL is delivering a memory solution that integrates both Flash and RAM products into one for the global niche memory semiconductor market with \$USD 4 billion constituting NOR Flash, FeRAM, PSRAM and low-power SRAM products, delivering better customer convenience and cost-effectiveness."

# • Forbes (<u>Article Link</u>) Posted : Jan.10.2023 by Tom Coughlin

2023 MRAM Forum Shows MRAM For Automotive And Other Applications



Netsol thinks that although currently MRAM is using existing memory interfaces, new memory interfaces will be needed for high performance standalone non-volatile memories. Netsol's roadmap has 14nm MRAM products introduced in late 2025 or 2026.

"At the 2023 MRAM Forum, a key event by the IEEE Magnetics Society tied to the IEDM conference, Mr. Noh, Chief Technology Officer at <u>Netsol</u>, provided an overview of the company's advancements in MRAM technology."

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# Press release

News

# • The ELEC Posted : Aug.10.2023 by Noh Taemin SRAM firm Netsol to supply Chinese firm with MRAM this year



South Korean chip fabless company Netsol is planning to supply its first magnetic random access memory (MRAM) to a Chinese customer, the company CEO told TheElec. Niche memory chips, excluding DRAM and NAND flash, accounted for 5% of the total memory chip market, Netsol CEO Kim Woo-jin said.

"The MRAM will be supplied to a Chinese industrial chip maker, which has placed a purchase order worth around US\$20,000. Netsol plans to use Samsung's 28nanometer process for the chip.Netsol is also planning to start development of next-generation 14nm spin transfer torque (STT)-MRAM after supplying its first MRAM."

# • MRAM-info (<u>Article Link</u>) Posted : Jan.10.2023 by Ron Mertens

Netsol Unveils First Standalone MRAM Using 28nm Process, Shares the Outlook for Standalone MRAM at 2023 MRAM Forum



At the 2023 MRAM Forum, a key event by the IEEE Magnetics Society tied to the IEDM conference, Mr. Noh, Chief Technology Officer at Netsol, provided an overview of the company's advancements in MRAM technology.

" Mr. Noh revealed Netsol's ongoing project: a 14nm Flash-like MRAM boasting high densities ranging from 128Mb to 1Gb, targeted specifically for the automotive application and expected to be released in the beginning of 2026..."

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# Press release

### News

# • Yahoo! finance Posted : Feb.1.2024

NETSOL Drives Automotive Innovation With Flash-like MRAM Breakthrough



The Best is yet to come THANK YOU!



New Evolution of Technology and SOLution



Memory. Storage. Solutions.

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